

09/435498

Abstract of the Disclosure

A back electrode type electronic part includes a main body including a circuit, and electrodes arranged for solder bumps on a back surface portion of the electronic part and connected to the circuit. Each of groups of the electrodes in portions of the electrode arrangement is provided for a single first solder bump which is larger than second solder bumps for the electrodes arranged other than the corner portions. Also, the group of electrodes includes electrodes having a substantially same potential level when the circuit operates.

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